ON Semiconductor®

Final Product/Process Change Notification

Document #:FPCN22701Z1
Issue Date:10 Dec 2020

Title of Change:	Update to FPCN22701Z1 – Cancellation of Mold compound conversion from EME-G750N to EME-G770HCD for X2DFN devices assembled in ON Semiconductor Leshan facility.
Proposed Changed Material First Ship Date:	10 Dec 2020
Current Material Last Order Date:	N/A *Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability***.**
Current Material Last Delivery Date:	N/A *The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory*
Product Category:	Active components – Discrete components
Contact information:	Contact your local ON Semiconductor Sales Office or Jim.Peng@onsemi.com
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office to place sample order or PCN.samples@onsemi.com Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Sample Availability Date:	N/A
PPAP Availability Date:	N/A
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 12 months prior to implementation of the change or earlier upon customer approval. ON Semiconductor will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com.

Change Category

Category	**Type of Change**
Process - Assembly	Change of mold compound

Description and Purpose:

This is an update notification of FPCN22701Z announces the cancellation of previously announced change.

As a result of this announcement the BOM will remain as the original BOM.

There are no product material changes as a result of this announcement.

There is no product marking change as a result of this announcement.

All of the list affected parts will still remain unchanged.

Reason / Motivation for Change:	Process/Materials Change
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by ON Semiconductor in relation to the PCN, associated risks are verified and excluded. No anticipated impacts.

Sites Affected:

ON Semiconductor Sites	External Foundry/Subcon Sites
Leshan Phoenix Semiconductor, China	None

Marking of Parts/ Traceability of Change:	Assembly Date Code

Reliability Data Summary:

N/A – FPCN22701Z is cancelled.

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: *Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the* ***PCN Customized Portal*****.**

Current Part Number	New Part Number	Qualification Vehicle
NSVR201MXT5G	NA	NSR0240MXWT5G
SZESD7241N2T5G	NA	SZESD7551MXWT5G
SZESD7410N2T5G	NA	NSPU3051N2T5G
SZESD7462N2T5G	NA	SZESD7551MXWT5G
SZESD7551N2T5G	NA	SZESD7551MXWT5G
SZESD7571N2T5G	NA	SZESD7551MXWT5G
SZESD8551N2T5G	NA	SZESD7551MXWT5G
SZESDM3551N2T5G	NA	NSPU3051N2T5G